

Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3 - \text{CaTiO}_3$ ($\epsilon_r = 21 / TC_f = 0 \pm 10 \text{ ppm/K}$) with a coating of copper ($10\mu\text{m}$) and tin ($>5\mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

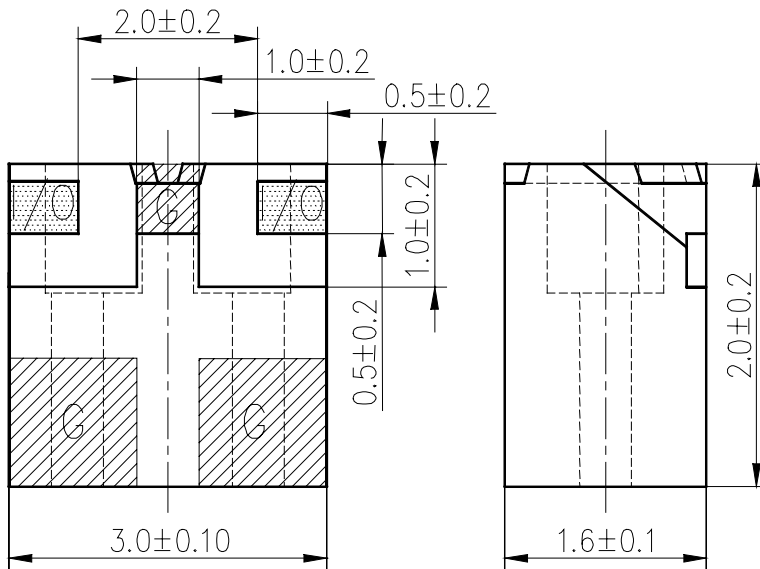
Index

- Page 2
 - Component drawing
 - Recommended footprint
- Page 3
 - Characteristics
 - Maximum ratings
 - Typical passband characteristic
- Page 4
 - Broadband characteristic
 - Processing information
 - Soldering requirements
- Page 5
 - Delivery mode

ISSUE DATE	19.03.04	ISSUE	P2	PUBLISHER	SAW MWC PD	PAGE	1/5
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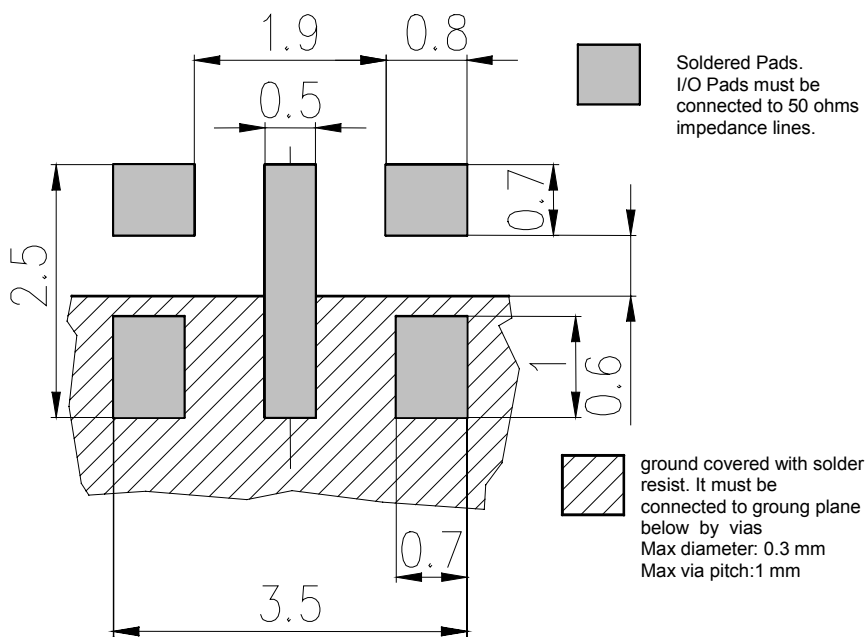
Preliminary Data Sheet

Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint



Preliminary Data Sheet

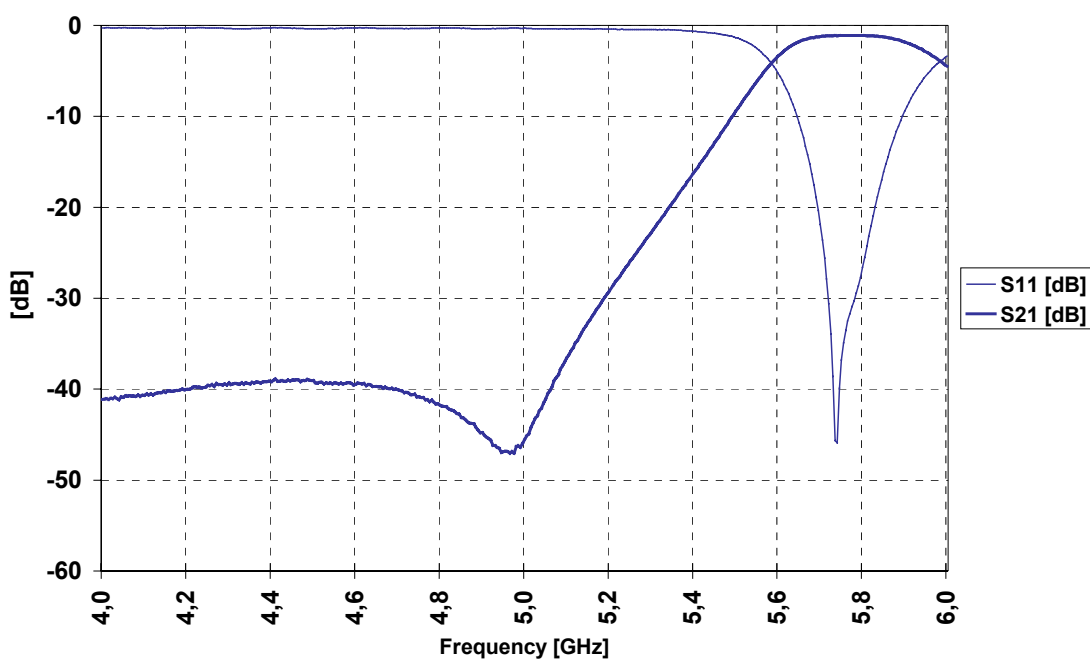
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	5.8	-	GHz
Insertion loss	α_{IL}		1.1	1.3	dB
Passband	B	150			MHz
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation	α				
	at DC to 1990 MHz	55	60		dB
	at 3300 MHz	40	46		dB
	at 5000 MHz	40	45		dB
	at 5425 MHz	12	15		dB
	at 6175 MHz	8	12		dB
	at 6800 MHz	25	27		dB

Maximum ratings

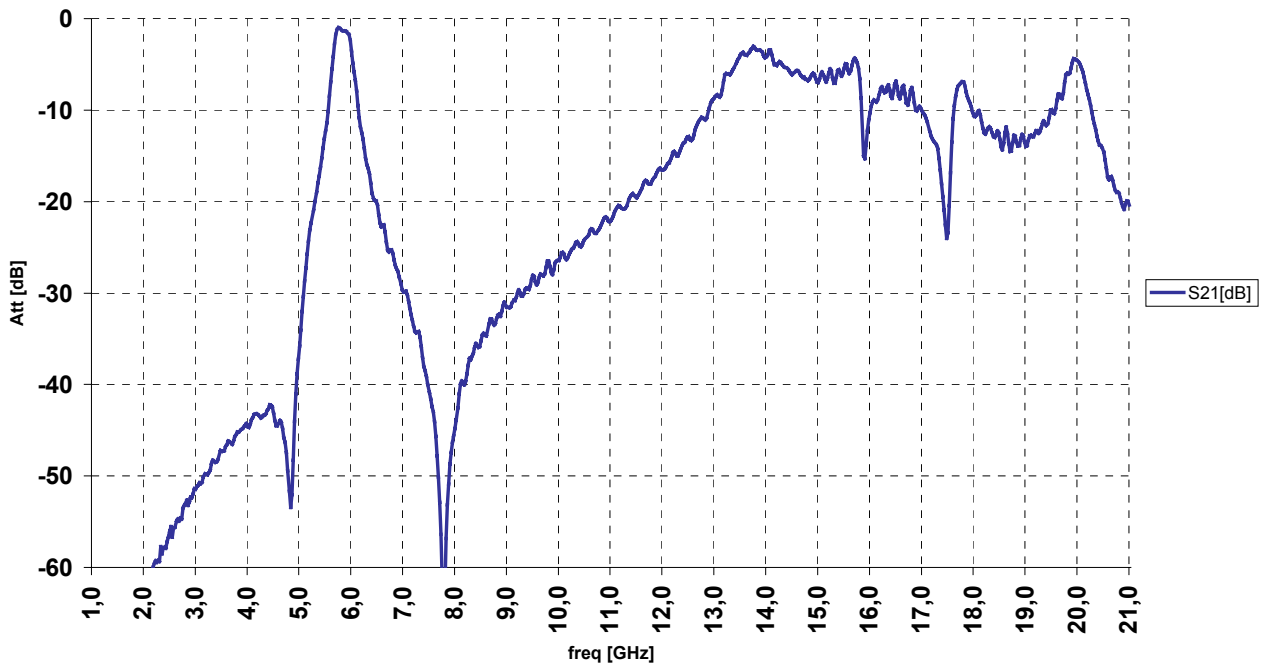
IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-40 / + 85	°C

Typical passband characteristic



Preliminary Data Sheet

Broadband characteristic



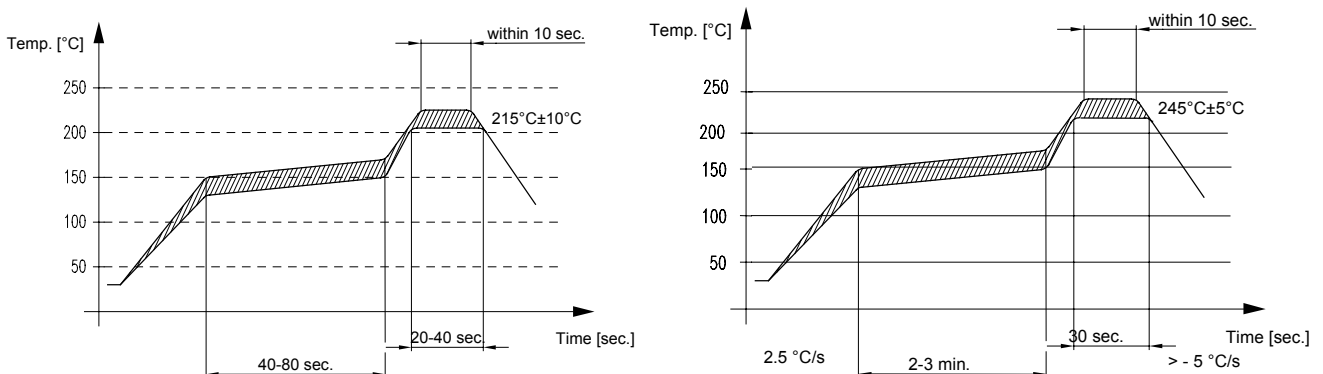
Processing information

- Wettability acc. to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):

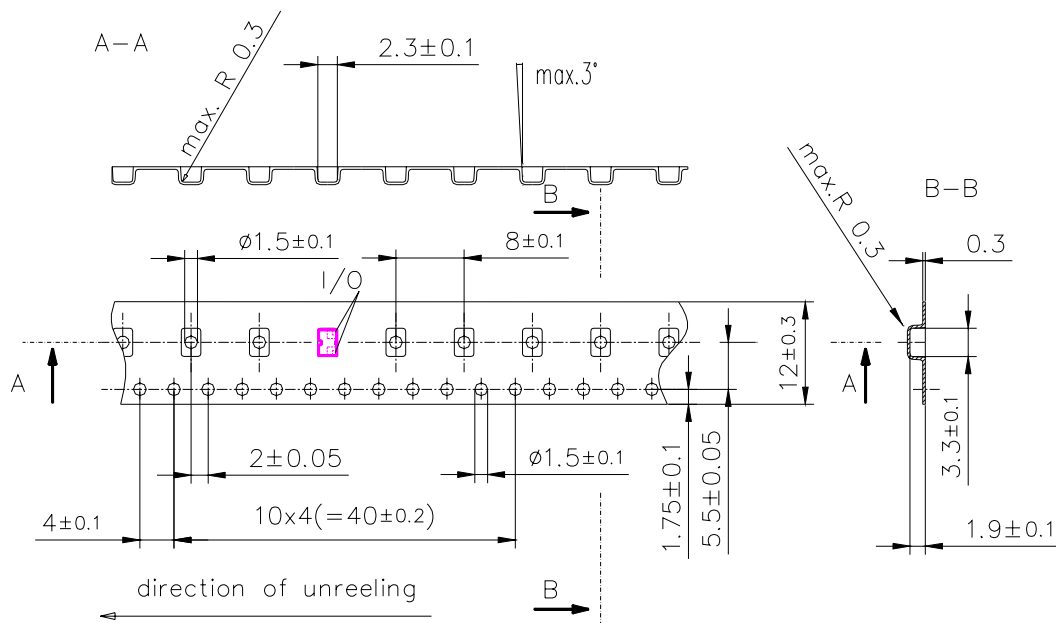


ISSUE DATE	19.03.04	ISSUE	P2	PUBLISHER	SAW MWC PD	PAGE	4/5
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Preliminary Data Sheet

Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 4000



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

ISSUE DATE	19.03.04	ISSUE	P2	PUBLISHER	SAW MWC PD	PAGE	5/5
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